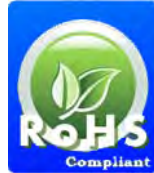
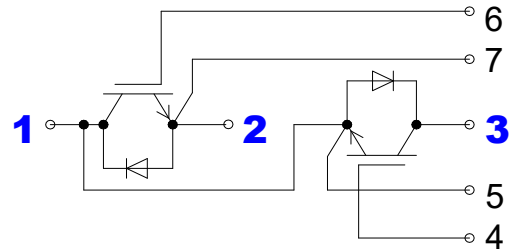


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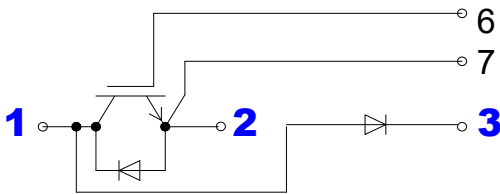
Ultra Fast IGBT Modules



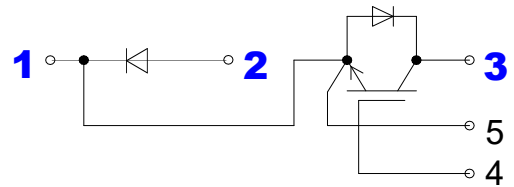
SGG300N125UC2



SGD100N125UC2



SDG100N125UC2



Symbol	Test Condition	Value	Unit
IGBT			
V _{CES}		1200	V
I _C	T _C = 25(80)°C per chip	300(210)	A
V _{GES}		±20	V
T _{vj} (T _{stg})		-40 ~ +150(125)	°C
P _{tot}		1670	W
INVERSE DIODE			
I _F	T _C =25(80)°C per chip	260(180)	A
I _{FM}	T _C =25(80)°C per chip	600(420)	A
V _{RRM}		1200	V
I _{FSM}	T _j =150°C, t _p =10ms	2250	A



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Ultra Fast IGBT Modules

Symbol	Test Conditions	Min	Typ	Max	Unit
IGBT Tc = 25°C unless otherwise specified					
V _{GE(th)}	V _{GE} =V _C E, I _C =6mA	4.5	5.5	6.5	V
I _{CES}	V _{GE} = 0; V _C E=V _C ES; T _j =25(125)°C		0.35(2.50)	0.55(3.00)	mA
V _C E(TO)	T _j =25(125)°C		1.7(1.5)	2.3(2.0)	V
r _{CE}	V _{GE} =15V T _j =25(125)°C		11.0(9.0)	12.0(10.5)	mΩ
V _C E(sat)	I _C =200A; V _{GE} =15V; chip level		3.30	3.75	V
C _{ies}	V _{GE} =0V, V _C E=25V, f=1MHz		18.0	24.0	nF
C _{oes}			2.60	3.00	
C _{res}			1.00	1.30	
L _{CE}				20	nH
R _{CC'+EE'}	Terminal to Case, T _c =25(125)°C		0.35(0.50)		mΩ
t _{d(on)}	V _{CC} = 600V, I _C = 200A R _{GOFF} = R _{GON} = 3Ω T _j =125°C V _{GE} =±15V		125		ns
t _r			39		ns
t _{d(off)}			460		ns
t _f			29		ns
E _{on} /E _{off}			16.0/11.0		mJ
INVERSE DIODE Tc = 25°C unless otherwise specified					
V _F	I _F =200A; V _{GE} =0V; T _j = 25°C		1.9	2.5	V
Q _{rr}	I _F =200A; V _R =300V; T _j =25°C di/dt = 600A/us, V _{GE} =-15V		9.5		μC
I _R RM			75		A
E _{rec}			15.0		mJ
THERMAL CHARACTERISTICS					
R _{th(j-c)}	per IGBT			0.075	K/W
R _{th(j-c)D}	per FRD			0.180	K/W
Mechanical Data					
M _s		2.5		5	Nm
Weight			320		g

Features

- NPT Technology IGBT
- Fast Recovery Free Wheeling Diode
- Low Switching Losses
- V_{ce}(sat) with positive temperature coefficient
- Fast Switching and short tail current
- Switched mode power supplies at f_{sw}>20KHz
- Resonant inverters up to 100KHz
- Electronic Welders at f_{sw}>20KHz

Application

- Welding inverters
- Inductive Heating

Advantages

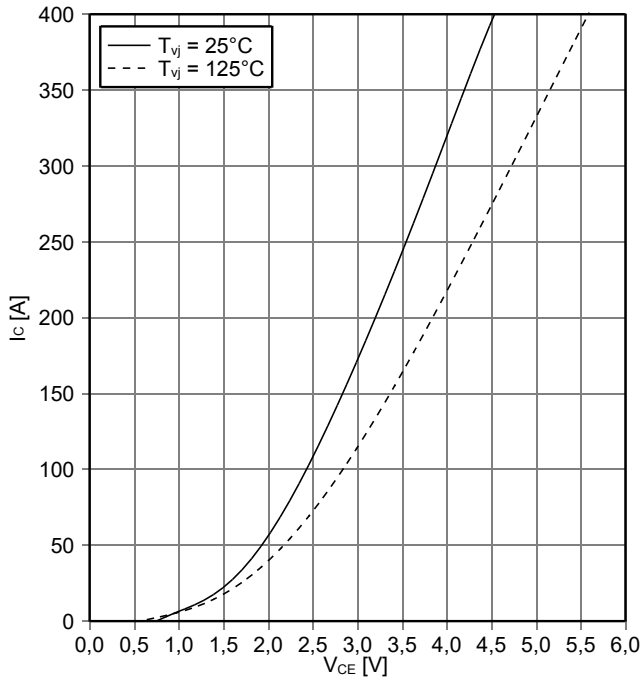
- Space and weight savings
- Reduced protection circuits

- This type IGBT can be direct replacement for SEMIKRON SKM300GB125D

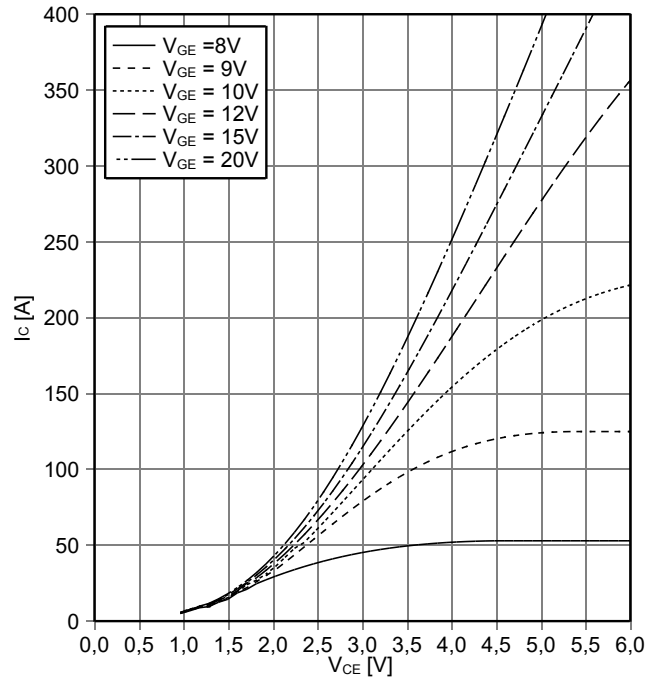


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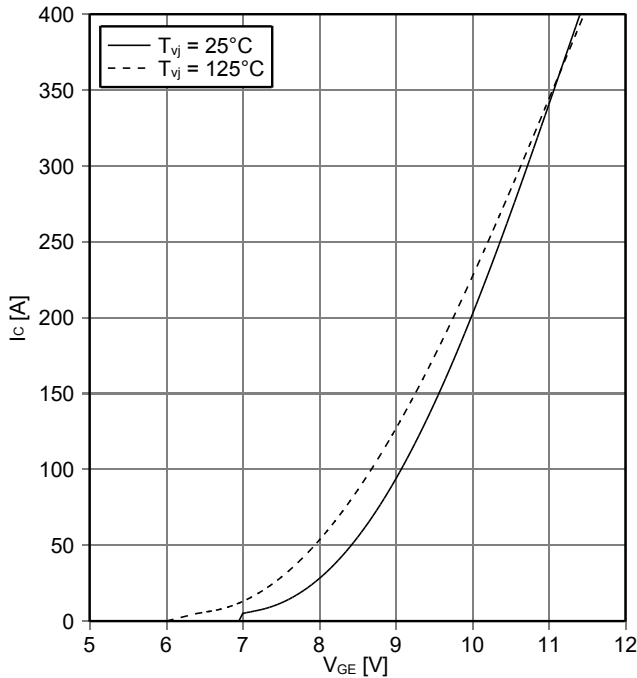
Ultra Fast IGBT Modules



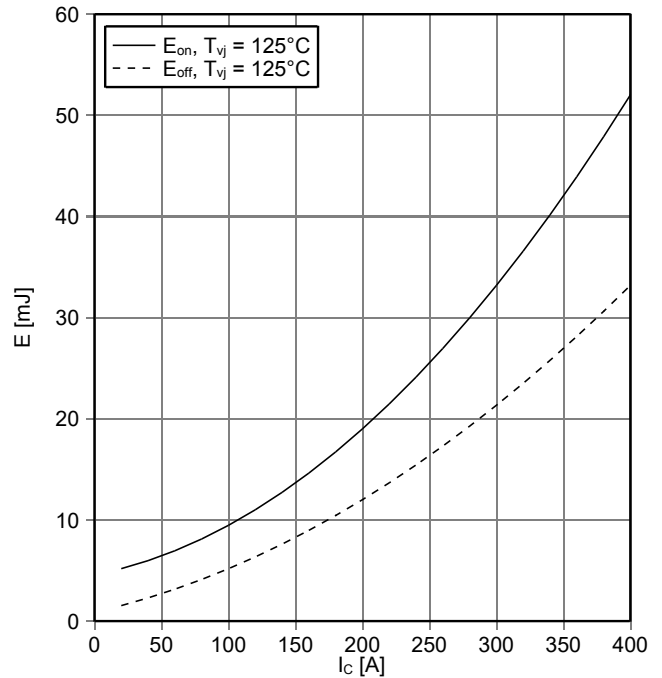
Output characteristic IGBT, Inverter (typical)
 $I_C = f(V_{CE}), V_{GE} = 15\text{ V}$



Output characteristic IGBT, Inverter (typical)
 $I_C = f(V_{CE}), T_{vj} = 125^\circ\text{C}$



Transfer characteristic IGBT, Inverter (typical)
 $I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$

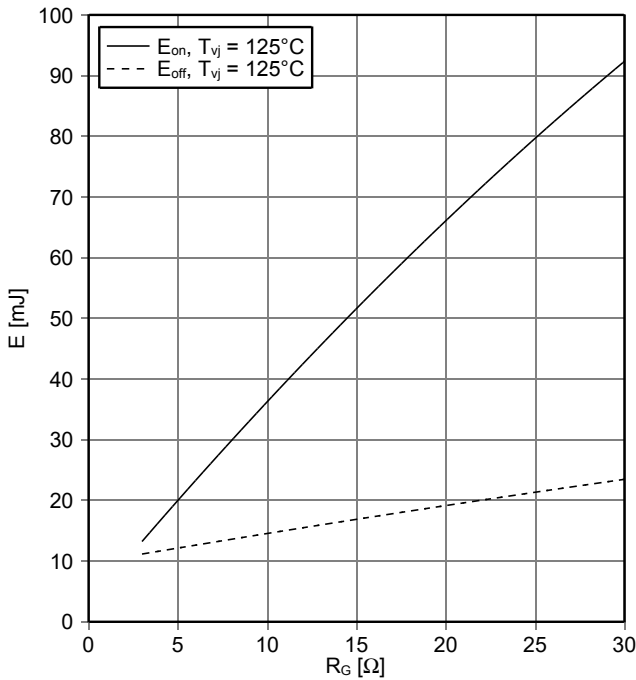


Switching losses IGBT, Inverter (typical)
 $E_{on} = f(I_C), E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 4.7\ \Omega, R_{Goff} = 4.7\ \Omega, V_{CE} = 600\text{ V}$

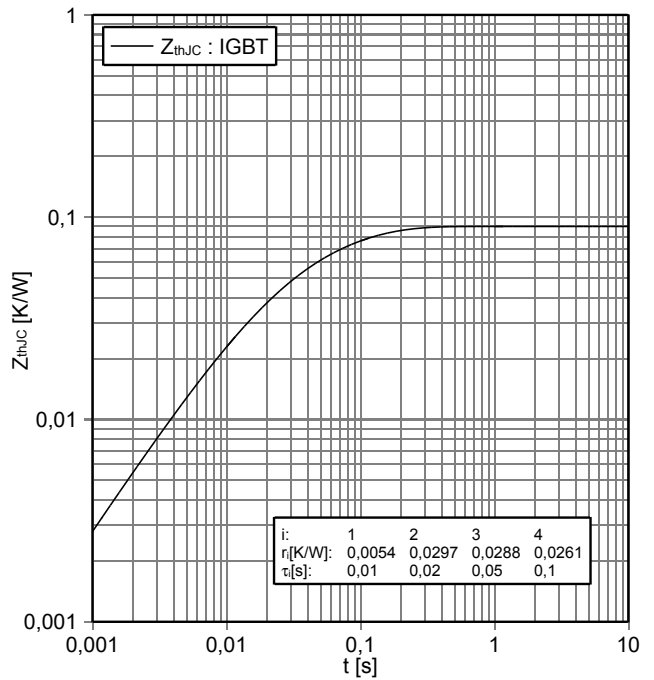


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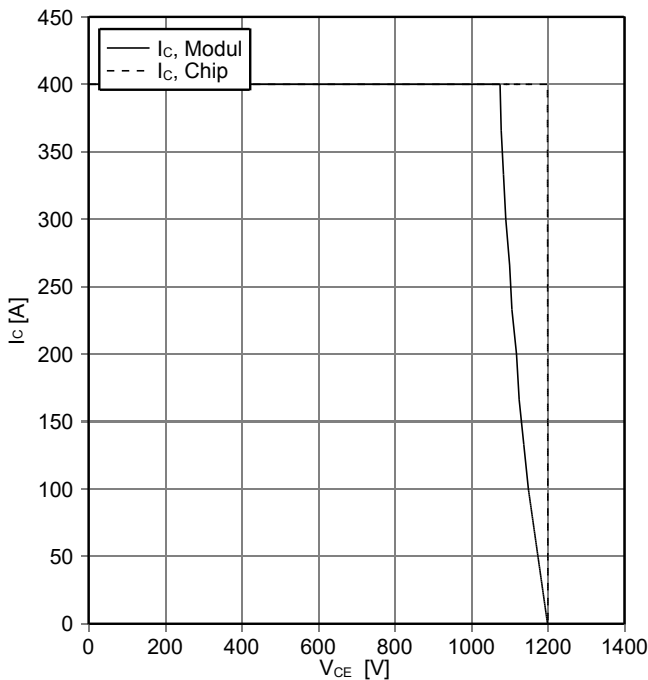


Switching losses IGBT, Inverter (typical)
 $E_{on} = f(R_G)$, $E_{off} = f(R_G)$
 $V_{GE} = \pm 15$ V, $I_C = 200$ A, $V_{CE} = 600$ V

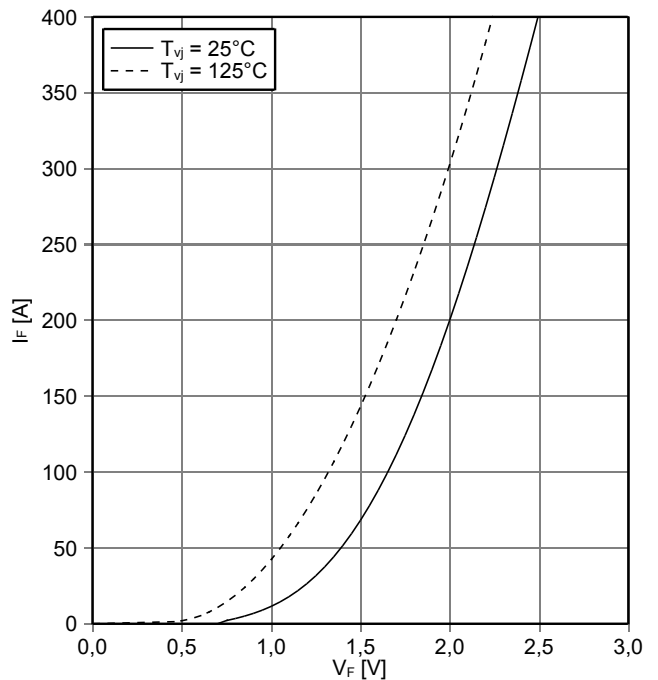


Transient thermal impedance IGBT, Inverter
 $Z_{thJC} = f(t)$

i :	1	2	3	4
r_f [K/W]:	0,0054	0,0297	0,0288	0,0261
τ_i [s]:	0,01	0,02	0,05	0,1



Reverse bias safe operating area IGBT, Inverter (RBSOA) $I_C = f(V_{CE})$
 $V_{GE} = \pm 15$ V, $R_{Goff} = 4.7$ Ω, $T_{vj} = 125^\circ\text{C}$

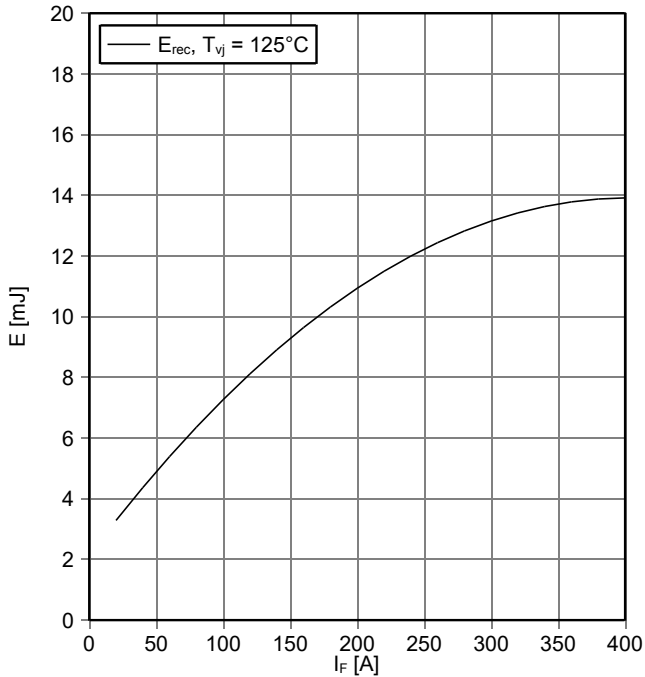


Forward characteristic of Diode, Inverter (typical)
 $I_F = f(V_F)$

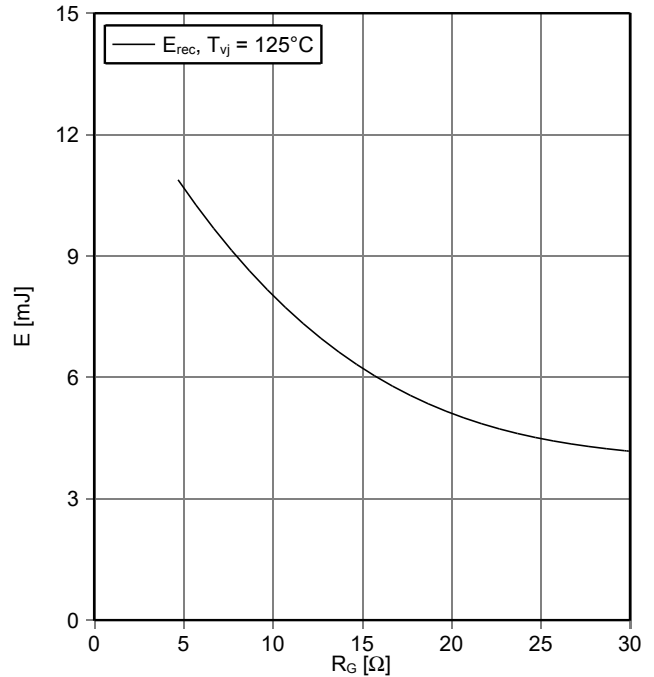


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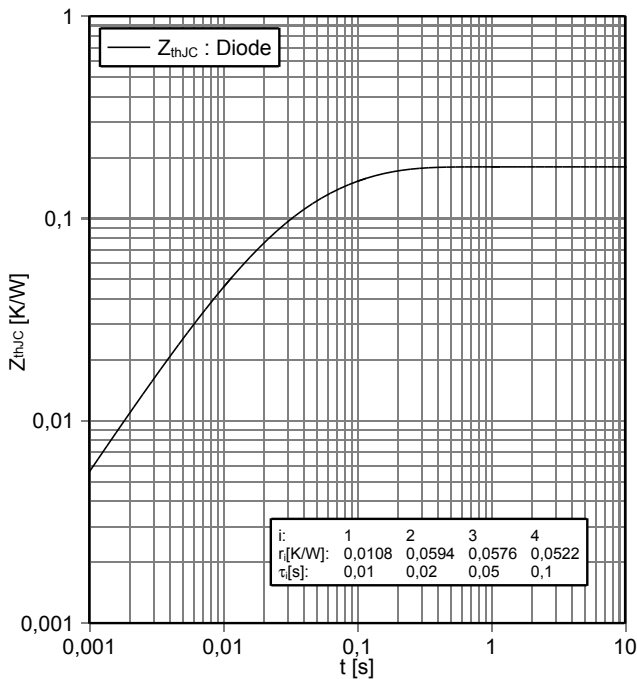
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Switching losses Diode, Inverter (typical)
 $E_{rec} = f(I_F)$
 $R_{Gon} = 4.7 \Omega, V_{CE} = 600 \text{ V}$



Switching losses Diode, Inverter (typical)
 $E_{rec} = f(R_G)$
 $I_F = 200 \text{ A}, V_{CE} = 600 \text{ V}$

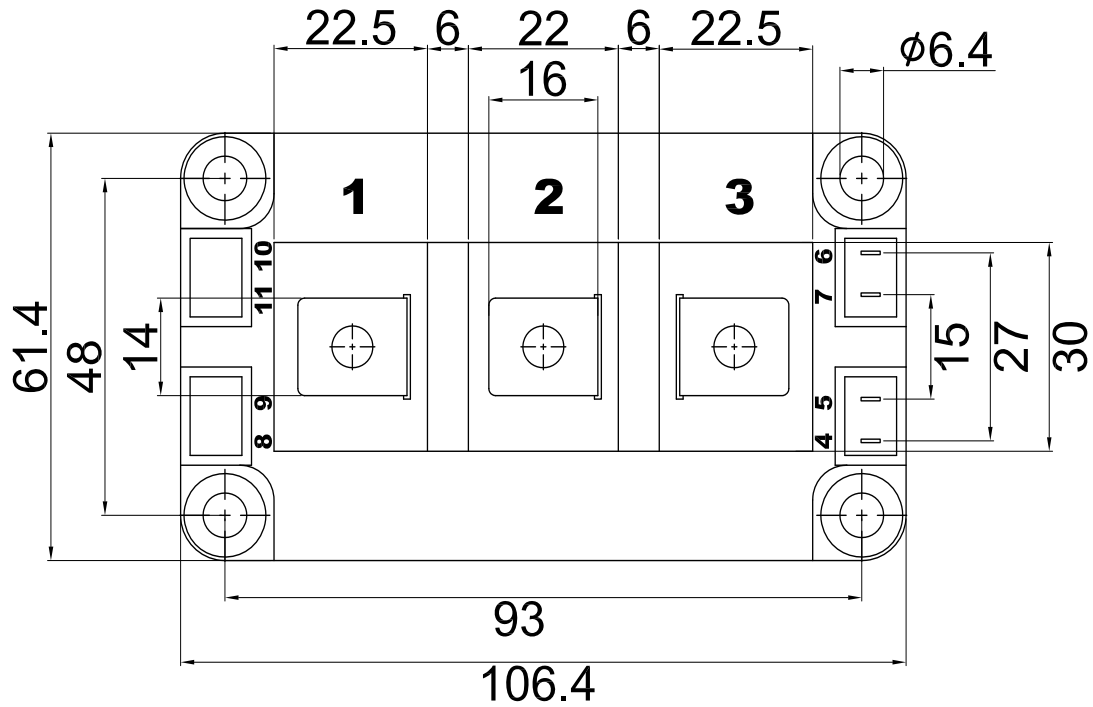
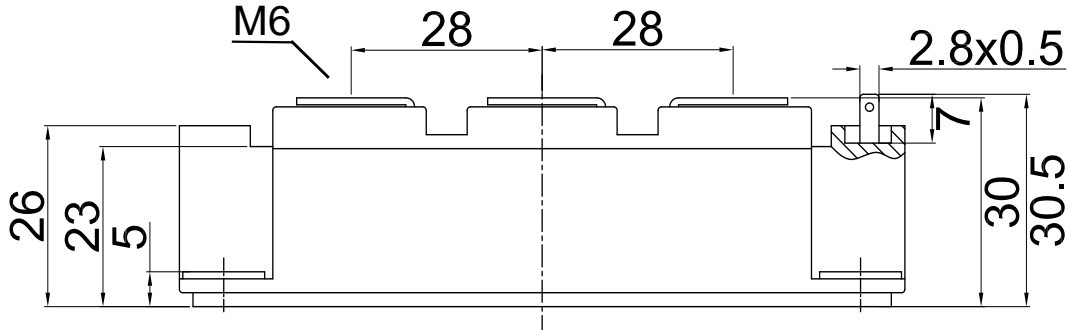


Transient thermal impedance Diode, Inverter
 $Z_{thJC} = f(t)$



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